



Material Content Data Sheet



Sales Product Name	TLE8209-2SA			Issued	9. May 2017			
MA#	MA001048810							
Package	PG-DSO-20-65			Weight*	2029.22 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.190	0.55	0.55	5514	5514
leadframe	inorganic material	phosphorus	7723-14-0	0.359	0.02		177	
	non noble metal	zinc	7440-66-6	1.435	0.07		707	
	non noble metal	iron	7439-89-6	28.697	1.41		14142	
wire	non noble metal	copper	7440-50-8	1165.200	57.43	58.93	574210	589236
	non noble metal	copper	7440-50-8	2.732	0.13	0.13	1346	1346
	encapsulation	organic material	carbon black	1333-86-4	1.597	0.08		787
plastics		epoxy resin	-	73.477	3.62		36210	
	inorganic material	silicondioxide	60676-86-0	723.593	35.66	39.36	356587	393584
leadfinish	non noble metal	tin	7440-31-5	10.336	0.51	0.51	5094	5094
plating	noble metal	silver	7440-22-4	0.686	0.03	0.03	338	338
solder	noble metal	silver	7440-22-4	0.149	0.01		73	
	non noble metal	tin	7440-31-5	0.099	0.00		49	
	non noble metal	lead	7439-92-1	9.671	0.48	0.49	4766	4888
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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